

Form PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION <i>(Use several sheets if necessary)</i>	Docket Number (Optional) 3640.2US (97-1175.02/US)	Application Number N t y t assigned
	Applicant St v n J. Simm ns	
	Filing Date August 29, 2003	Group Art Unit Unkn wn

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>MSL</i>	4,376,583	03/1983	Alford et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	5,103,166	04/1992	Jeon et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	5,127,726	07/1992	Moran	<i>1</i>	<i>1</i>	
<i>MSL</i>	5,240,866	08/1993	Friedman et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	5,294,812	03/1994	Hashimoto et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	5,301,143	04/1994	Ohri et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	5,539,752	07/1996	Berezin et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	5,544,256	08/1996	Brecher et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	5,777,901	07/1998	Berezin et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	6,265,232	07/2001	Simmons	<i>1</i>	<i>1</i>	
<i>MSL</i>	6,479,305	11/2002	Kono et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	6,485,991	11/2002	Jitramas et al.	<i>1</i>	<i>1</i>	
<i>MSL</i>	6,492,189	12/2002	Yamaguchi	<i>1</i>	<i>1</i>	
<i>MSL</i>	6,613,590	09/2003	Simmons	<i>1</i>	<i>1</i>	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

<i>MSL</i>		S.L. Riley, "Optical Inspection of Wafers Using Large-Area Defect Detection and Sampling", The IEEE International Workshop on Defect and Fault Tolerance in VLSI Systems, November 4-6 1992, pps. 12-21.
<i>MSL</i>		KLA 255X Software V3.6 Option Release Notes, "Automatic Clustering and Sampling of Defects", 19 pages. <i>10/20/02</i>

EXAMINER <i>[Signature]</i>	DATE CONSIDERED <i>6/18/04</i>
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance. Include copy of this form with next communication to the applicant.